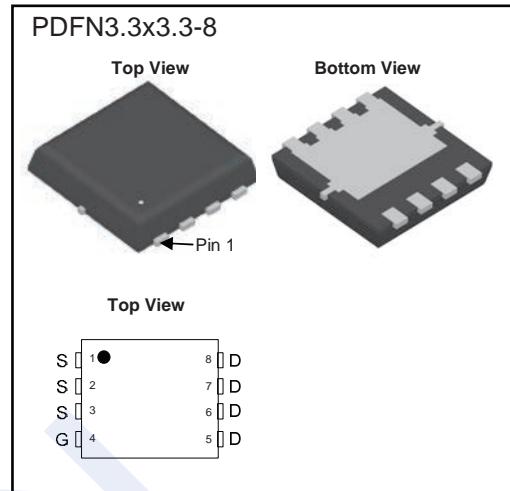
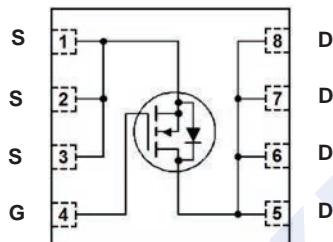


## N-Channel MOSFET

## 2KK5778DFN

## ■ Features

- $V_{DS}$  (V) = 60 V
- $I_D$  = 41 A @  $V_{GS}$ =10V
- $R_{DS(ON)}$  = 7.5mΩ (typ.) @  $V_{GS}$ =10V
- $R_{DS(ON)}$  = 9.4mΩ (typ.) @  $V_{GS}$ =4.5V

■ Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current (1)	$I_D$	41	A
		26	
Pulsed Drain Current (2)	$I_{DM}$	147	A
Avalanche Current, Single pulse (3)	$I_{AS}$	26	
Avalanche Energy, Single pulse (3)	$E_{AS}$	34	mJ
Power Dissipation (4)	$P_D$	28	W
		11.1	
Thermal Resistance.Junction- to-Case	$R_{\theta JC}$	4.5	$^\circ\text{C}/\text{W}$
Thermal Resistance.Junction- to-Ambient	$R_{\theta JA}$	62	
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to 150	

Notes 1. Computed continuous current assumes the condition of  $T_J_{Max}$  while the actual continuous current depends on the thermal & electro-mechanical application board design.

2. This single-pulse measurement was taken under  $T_J_{Max} = 150^\circ\text{C}$ .
3. This single-pulse measurement was taken under the following condition ( $L = 100\mu\text{H}$ ,  $V_{GS} = 10\text{V}$ ,  $V_{DS} = 30\text{V}$ ) while its value is limited by  $T_J_{Max} = 150^\circ\text{C}$ .
4. The power dissipation  $P_D$  is based on  $T_J_{Max} = 150^\circ\text{C}$ .

**N-Channel MOSFET****2KK5778DFN****■ Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{Id} = 250 \mu\text{A}, \text{V}_{\text{GS}} = 0\text{V}$	60			V
Zero Gate Voltage Drain Current	$\text{Id}_{\text{SS}}$	$\text{V}_{\text{DS}} = 48 \text{ V}, \text{V}_{\text{GS}} = 0 \text{ V}$		1		$\mu\text{A}$
		$\text{V}_{\text{DS}} = 48 \text{ V}, \text{V}_{\text{GS}} = 0 \text{ V}, \text{T}_J = 55^\circ\text{C}$		5		
Gate to Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{DS}} = 0 \text{ V}, \text{V}_{\text{GS}} = \pm 20 \text{ V}$			$\pm 100$	nA
Gate to Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{Id} = 250 \mu\text{A}$	1.2		2.5	V
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{Id} = 20 \text{ A}$		7.5	9.4	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5 \text{ V}, \text{Id} = 15 \text{ A}$		9.4	12.2	
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}} = 5\text{V}, \text{Id} = 20\text{A}$		85		S
Diode Forward Voltage	$\text{V}_{\text{SD}}$	$\text{I}_{\text{S}} = 1\text{A}, \text{V}_{\text{GS}} = 0\text{V}$			1	V
Diode Continuous Current	$\text{I}_{\text{S}}$				28	A
<b>Dynamic Parameters (5)</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{V}_{\text{DS}} = 30 \text{ V}, \text{f} = 1 \text{ MHz}$		1087		$\text{pF}$
Output Capacitance	$\text{C}_{\text{oss}}$			309		
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$			8.5		
Gate Resistance	$\text{R}_{\text{g}}$	$\text{V}_{\text{GS}} = 0 \text{ V}, \text{V}_{\text{DS}} = 0 \text{ V}, \text{f} = 1 \text{ MHz}$		1.6		$\Omega$
<b>Switching Parameters (5)</b>						
Total Gate Charge ( $\text{V}_{\text{GS}}=10\text{V}$ )	$\text{Q}_{\text{g}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{V}_{\text{DS}} = 30 \text{ V}, \text{I}_{\text{DS}} = 20 \text{ A}$		16.6		$\text{nC}$
Total Gate Charge ( $\text{V}_{\text{GS}}=4.5\text{V}$ )	$\text{Q}_{\text{gs}}$			8.3		
Gate Source Charge	$\text{Q}_{\text{gd}}$			2.6		
Gate Drain Charge	$\text{Q}_{\text{gd}}$			2.7		
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{GS}} = 10 \text{ V}, \text{V}_{\text{DS}} = 30 \text{ V}$ $\text{R}_{\text{L}} = 1.5 \Omega, \text{R}_{\text{GEN}} = 6 \Omega$		4.7		$\text{ns}$
Turn-On Rise Time	$\text{t}_{\text{r}}$			7.6		
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$			24		
Turn-Off Fall Time	$\text{t}_{\text{f}}$			8.9		
Body Diode Reverse Recovery Time	$\text{t}_{\text{rr}}$	$\text{I}_{\text{F}} = 15 \text{ A}, \frac{\text{dI}}{\text{dt}} = 100 \text{ A}/\mu\text{s}$		26		$\text{nC}$
Body Diode Reverse Recovery Charge	$\text{Q}_{\text{rr}}$			13.4		

Note 5. This value is guaranteed by design hence it is not included in the production test.

**■ Marking**

2KK5778DFN	K5778 KC***
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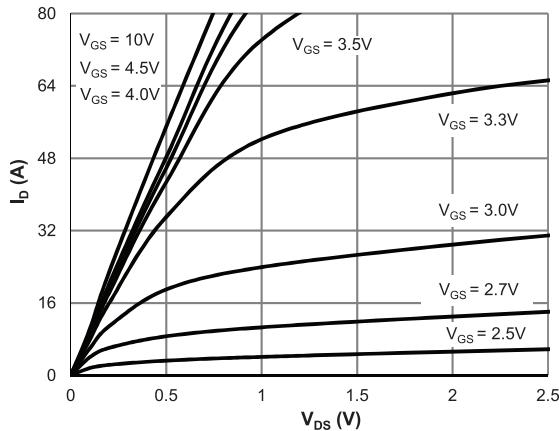
**N-Channel MOSFET****2KK5778DFN****■ Typical Characteristics & Thermal Characteristics**

Figure 1: Saturation Characteristics

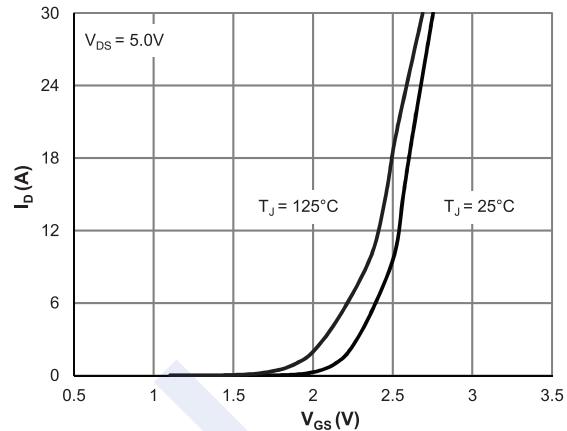


Figure 2: Transfer Characteristics

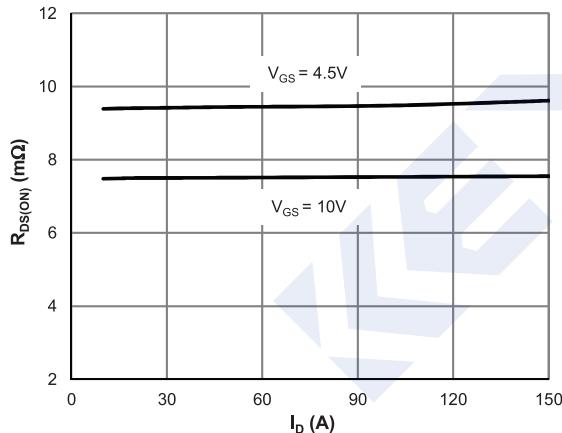
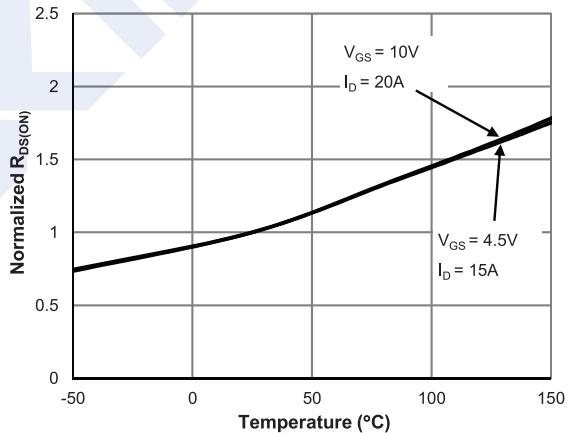
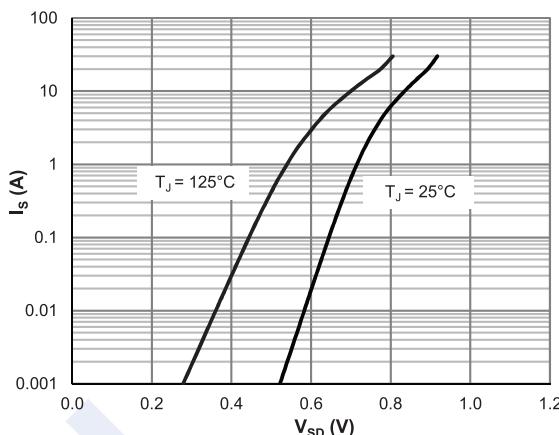
Figure 3:  $R_{DS(ON)}$  vs. Drain CurrentFigure 4:  $R_{DS(ON)}$  vs. Junction Temperature

Figure 5: Body-Diode Characteristics

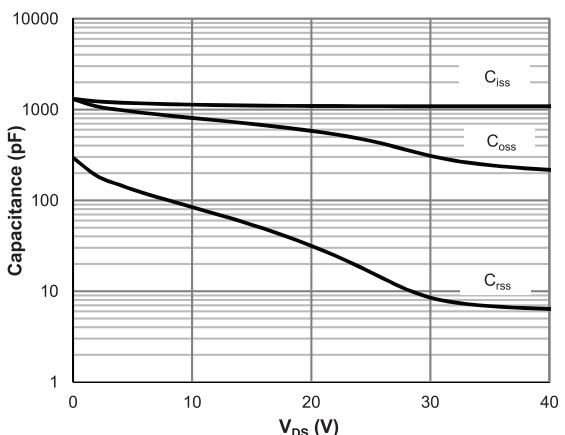


Figure 6: Capacitance Characteristics

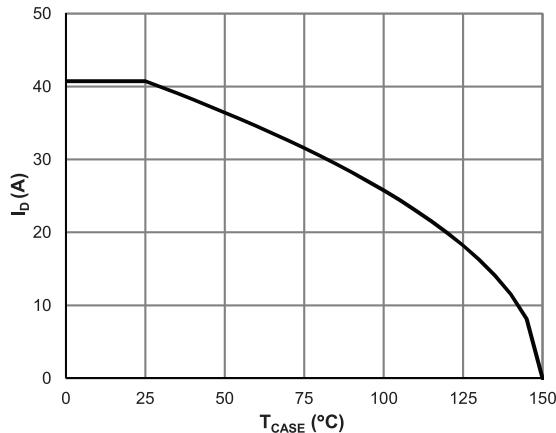
**N-Channel MOSFET****2KK5778DFN**

Figure 7: Current De-rating

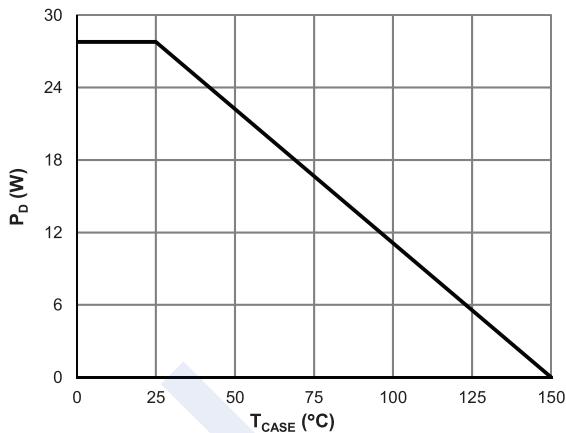


Figure 8: Power De-rating

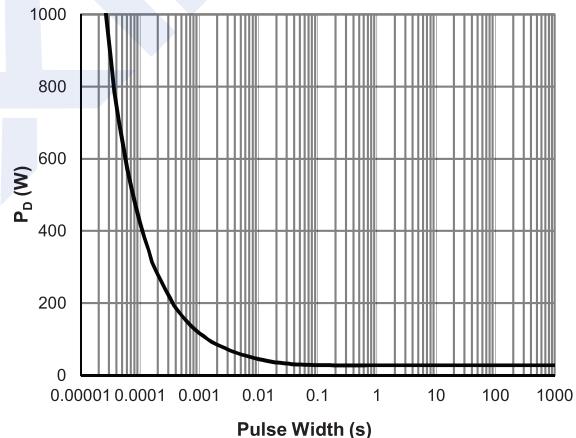
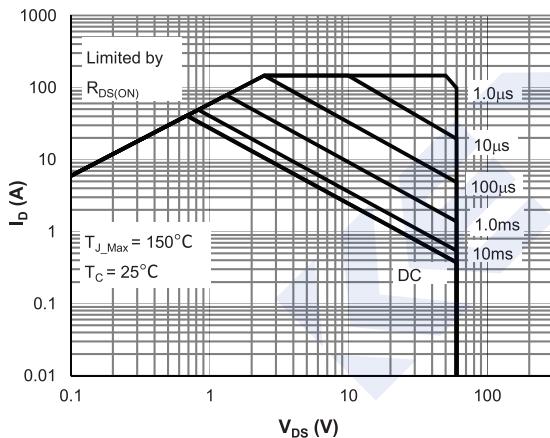


Figure 10: Single Pulse Power Rating, Junction-to-Case

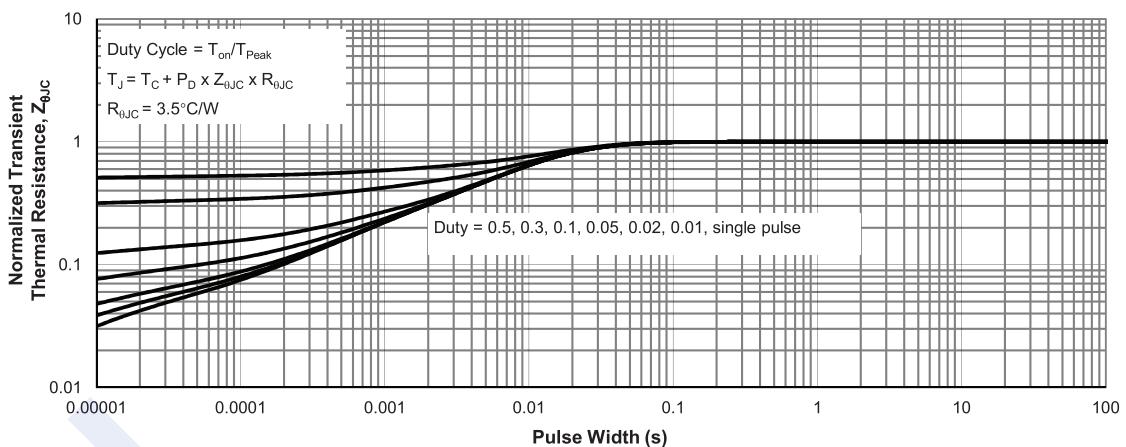
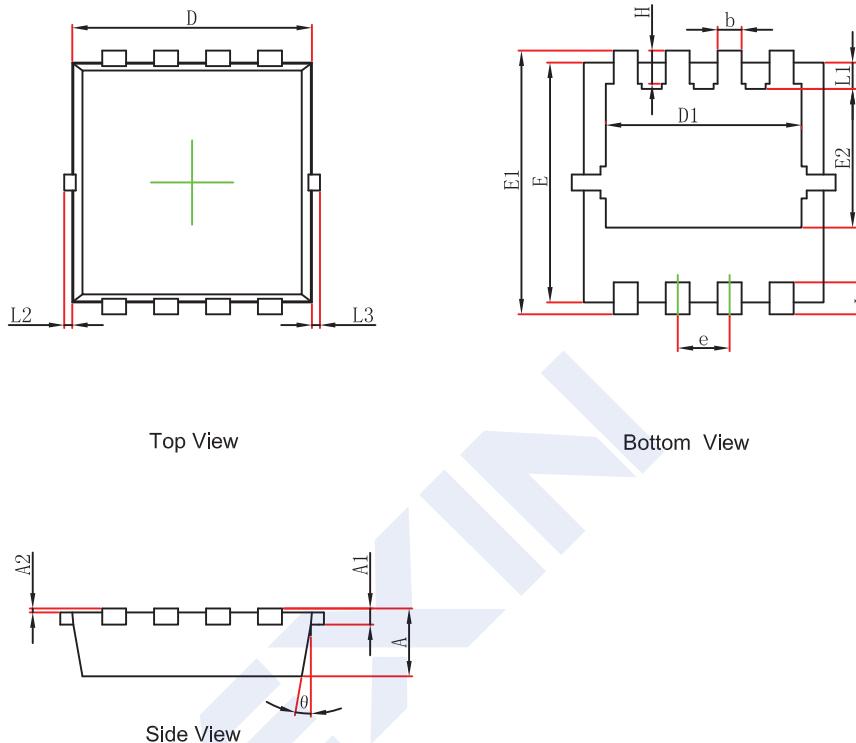


Figure 11: Normalized Maximum Transient Thermal Impedance

## N-Channel MOSFET

## 2KK5778DFN

## ■ PDFN3.3x3.3-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.			0.006 REF.
A2	0~0.05			0~0.002
D	3.050	3.250	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100			0~0.004
L3	0~0.100			0~0.004
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°